



Material Content Data Sheet



Sales Product Name		BSC009NE2LS5		Issued		1. August 2018		
MA#		MA001381618						
Package		PG-TDSON-8-7		Weight*		115.77 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.699	0.60	0.60	6036	6036
leadframe	inorganic material	phosphorus	7723-14-0	0.015	0.01		127	
	non noble metal	iron	7439-89-6	0.049	0.04		425	
	non noble metal	copper	7440-50-8	49.082	42.41	42.46	423977	424529
	non noble metal	copper	7440-50-8	0.021	0.02	0.02	179	179
wire	non noble metal	copper	7440-50-8	0.021	0.02	0.02	179	179
encapsulation	organic material	carbon black	1333-86-4	0.082	0.07		708	
	plastics	epoxy resin	-	6.475	5.59		55929	
	inorganic material	silicondioxide	60676-86-0	34.422	29.73	35.39	297344	353981
leadfinish	non noble metal	tin	7440-31-5	1.452	1.25	1.25	12540	12540
plating	noble metal	silver	7440-22-4	0.166	0.14	0.14	1430	1430
solder	non noble metal	tin	7440-31-5	0.020	0.02		170	
	noble metal	silver	7440-22-4	0.025	0.02		212	
	non noble metal	lead	7439-92-1	0.939	0.81	0.85	8113	8495
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.007	0.01		58	
	non noble metal	iron	7439-89-6	0.022	0.02		193	
	non noble metal	copper	7440-50-8	22.292	19.26	19.29	192559	192810
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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